

#### **ABSOLUTE MAXIMUM RATINGS** at $T_A = 25^{\circ}C$

Logic Supply Voltage, V <sub>DD</sub>	15 V
Driver Supply Voltage, V <sub>BB</sub>	60 V
Continuous Output Current Range,	
I <sub>OUT</sub> 40 to +15	mA
Input Voltage Range,	
V <sub>IN</sub> 0.3 V to V <sub>DD</sub> + 0	).3 V
Package Power Dissipation, P <sub>D</sub>	
(UCQ5812AF)	2 W*
(UCQ5812EPF)	W†

Operating Temperature Range,

T<sub>A</sub> .....-40°C to +85°C

Storage Temperature Range,

T<sub>S</sub> ......-55°C to +150°C

- \* Derate at rate of 22 mW/°C above T<sub>A</sub> = +25°C
- † Derate at rate of 15 mW/°C above T<sub>A</sub> = +25°C

Caution: Allegro CMOS devices have input static protection but are susceptible to damage when exposed to extremely high static electrical charges.

Note that the UCQ5812AF (dual in-line package) and UCQ5812EPF (PLCC package) are electrically identical and share a common pin number assignment.

The UCQ5812AF/EPF combine a 20-bit CMOS shift register, data latches, and control circuitry with high-voltage bipolar source drivers and active DMOS pull-downs for reduced supply current requirements. Although designed primarily for vacuum-fluorescent displays, the high-voltage, highcurrent outputs also allow them to be used in other peripheral power driver applications.

The CMOS shift register and latches allow direct interfacing with microprocessor-based systems. With a 5 V supply, they will operate to at least 3.3 MHz. At 12 V, higher speeds are possible. Especially useful for inter-digit blanking, the BLANKING input disables the output source drives and turns on the DMOS sink drivers. Use with TTL may require the use of appropriate pull-up resistors to ensure an input logic high.

A CMOS serial data output enables cascade connections in applications requiring additional drive lines. Similar devices are available as the UCQ5810AF/LWF (10 bits), UCQ5811A (12 bits), and UCQ5818AF/EPF (32 bits).

The output source drivers are high-voltage PNP-NPN Darlingtons with a minimum breakdown of 60 V and are capable of sourcing up to 40 mA. The DMOS active pull-downs are capable of sinking up to 15 mA.

The UCQ5812AF is supplied in a 28-pin dual in-line plastic package with 0.600" (15.24 mm) row spacing. For surface mounting, the UCQ5812EPF is furnished in 28-lead plastic chip carrier (quad pack) with 0.050"(1.22 mm) centers. Copper lead-frames, reduced supply current requirements and lower output saturation voltages, allow continuous operation, with all outputs sourcing 25 mA, of the UCQ5812AF over the operating temperature range, and the UCQ5812EPF up to  $+75^{\circ}$ C.

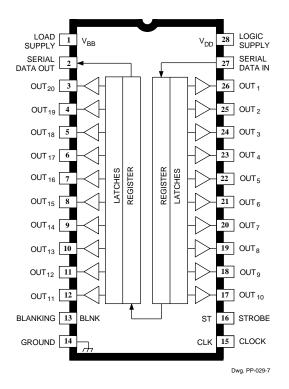
#### **FEATURES**

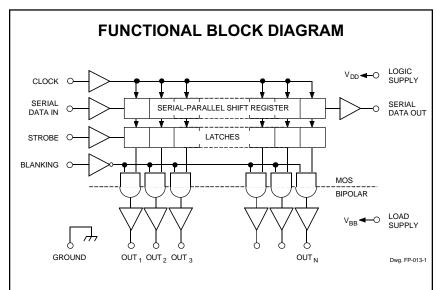
- High-Speed Source Drivers
- 60 V Source Outputs
- To 3.3 MHz Data Input Rate
- Low-Output Saturation Voltages
- Low-Power CMOS Logic and Latches
- Active DMOS Pull-Downs
- Reduced Supply Current Requirements
- Improved Replacement for TL5812

Always order by complete part number, e.g., | UCQ5812AF | .

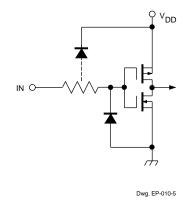


#### **UCQ5812AF**

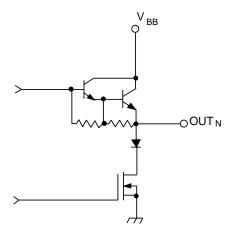




#### TYPICAL INPUT CIRCUIT



#### TYPICAL OUTPUT DRIVER



Dwg. No. A-14,219

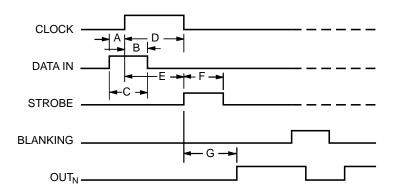


# ELECTRICAL CHARACTERISTICS over operating temperature range, at $V_{BB}$ = 60 V (unless otherwise noted).

			Limits @ V <sub>DD</sub> = 5 V		Limits				
Characteristic	Symbol	Test Conditions	MIn.	Тур.	Max.	Min.	Тур.	Max.	Units
Output Leakage Current	I <sub>CEX</sub>	$V_{OUT} = 0 \text{ V}, T_A = +70^{\circ}\text{C}$	_	-5.0	-15	_	-5.0	-15	μΑ
Output Voltage	V <sub>OUT(1)</sub>	I <sub>OUT</sub> = -25 mA, V <sub>BB</sub> = 60 V	58	58.5	_	58	58.5	_	V
	V <sub>OUT(0)</sub>	I <sub>OUT</sub> = 1 mA	_	2.0	3.0	_	_	_	V
		I <sub>OUT</sub> = 2 mA	_	_	_	_	2.0	3.5	V
Output Pull-Down Current	I <sub>OUT(0)</sub>	$V_{OUT} = 5 \text{ V to } V_{BB}$	2.0	3.5	_	_	_	_	mA
		$V_{OUT} = 20 \text{ V to } V_{BB}$	_	_	_	8.0	13	_	mA
Input Voltage	V <sub>IN(1)</sub>		3.5	_	5.3	10.5	_	12.3	V
	V <sub>IN(0)</sub>		-0.3	_	+0.8	-0.3	_	+0.8	V
Input Current	I <sub>IN(1)</sub>	$V_{IN} = V_{DD}$	_	0.05	0.5	_	0.1	1.0	μΑ
	I <sub>IN(0)</sub>	V <sub>IN</sub> = 0.8 V	_	-0.05	-0.5	_	-0.1	-1.0	μΑ
Serial Data	V <sub>OUT(1)</sub>	I <sub>OUT</sub> = -200 μA	4.5	4.7	_	11.7	11.8	_	V
	V <sub>OUT(0)</sub>	I <sub>OUT</sub> = 200 μA	_	200	250	_	100	200	mV
Maximum Clock Frequency	f <sub>clk</sub>		3.3*	_	_	_	_	_	MHz
Supply Current	I <sub>DD(1)</sub>	All Outputs High	_	100	300	_	200	500	μΑ
	I <sub>DD(0)</sub>	All Outputs Low	_	100	300	_	200	500	μΑ
	I <sub>BB(1)</sub>	Outputs High, No Load	_	1.5	4.0	_	1.5	4.0	mA
	I <sub>BB(0)</sub>	Outputs Low	_	10	100	_	10	100	μΑ
Blanking to Output Delay	t <sub>PHL</sub>	C <sub>L</sub> = 30 pF, 50% to 50%	_	2000	_	_	1000	_	ns
	t <sub>PLH</sub>	C <sub>L</sub> = 30 pF, 50% to 50%	_	1000	_	_	850	_	ns
Output Fall Time	t <sub>f</sub>	C <sub>L</sub> = 30 pF, 90% to 10%	_	1450	_	_	650	_	ns
Output Rise Time	t <sub>r</sub>	C <sub>L</sub> = 30 pF, 10% to 90%	_	650	_		700	_	ns

Negative current is defined as coming out of (sourcing) the specified device pin.

<sup>\*</sup> Operation at a clock frequency greater than the specified minimum value is possible but not warranteed.



Dwg. No. 12,649A

#### TIMING REQUIREMENTS

 $(T_A = +25^{\circ}C, V_{DD} = 5 \text{ V}, \text{Logic Levels are } V_{DD} \text{ and Ground})$ 

A.	Minimum Data Active Time Before Clock Pulse (Data Set-Up Time)	. 75 ns
В.	Minimum Data Active Time After Clock Pulse (Data Hold Time)	. 75 ns
C.	Minimum Data Pulse Width	150 ns
D.	Minimum Clock Pulse Width	150 ns
E.	Minimum Time Between Clock Activation and Strobe	300 ns
F.	Minimum Strobe Pulse Width	100 ns
G.	Typical Time Between Strobe Activation and	
	Output Transistion	500 ns

Timing is representative of a 3.3 MHz clock. Higher speeds may be attainable with increased supply voltage; operation at high temperatures will reduce the specified maximum clock frequency.

Serial Data present at the input is transferred to the shift register on the logic "0" to logic "1" transition of the CLOCK input pulse. On succeeding CLOCK pulses, the registers shift data information towards the SERIAL DATA OUT-PUT. The SERIAL DATA must appear at the input prior to the rising edge of the CLOCK input waveform.

Information present at any register is transferred to the respective latch when the STROBE is high (serial-to-parallel conversion). The latches will continue to accept new data as long as the STROBE is held high. Applications where the latches are bypassed (STROBE tied high) will require that the BLANKING input be high during serial data entry.

When the BLANKING input is high, the output source drivers are disabled (OFF); the DMOS sink drivers are ON, the information stored in the latches is not affected by the BLANKING input. With the BLANKING input low, the outputs are controlled by the state of their respective latches.

#### **TRUTH TABLE**

Serial		Shif	ft Re	gist	er C	ontents	Serial		Latch Contents			Output Contents				ents			
Data	Clock						Data	Strobe					1						
Input	Input	I <sub>1</sub>	$I_2$	$I_3$		$I_{N-1}$ $I_{N}$	Output	Input	I <sub>1</sub>	l <sub>2</sub>	l <sub>3</sub>	 $I_{N-1}$ $I_{N}$	Blanking	I <sub>1</sub>	l <sub>2</sub>	l <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>
Н	7	Н	R <sub>1</sub>	$R_2$		$R_{N-2}R_{N-1}$	R <sub>N-1</sub>												
L		L	$R_1$	$R_2$		$R_{N-2}R_{N-1}$	R <sub>N-1</sub>												
Х	l	R <sub>1</sub>	R <sub>2</sub>	R <sub>3</sub>		$R_{N-1}R_N$	R <sub>N</sub>												
		Х	Χ	Χ		ХХ	Х	L	R <sub>1</sub>	$R_2$	$R_3$	 R <sub>N-1</sub> R <sub>N</sub>							
		P <sub>1</sub>	$P_2$	$P_3$		$P_{N-1}$ $P_{N}$	P <sub>N</sub>	Н	P <sub>1</sub>	$P_2$	$P_3$	 P <sub>N-1</sub> P <sub>N</sub>	L	P <sub>1</sub>	$P_2$	$P_3$		P <sub>N1</sub>	$P_N$
									X	Χ	Χ	 ХХ	Н	L	L	L		L	L

L = Low Logic Level H = High Logic Level

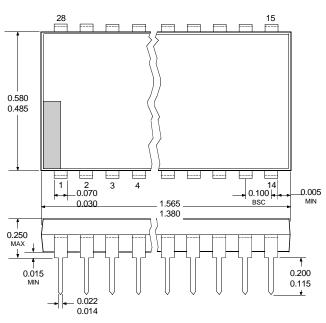
X = Irrelevant

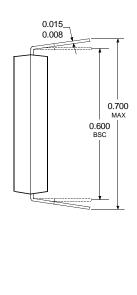
P = Present State R = Previous State



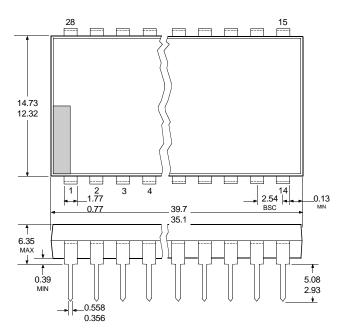
#### **UCQ5812AF**

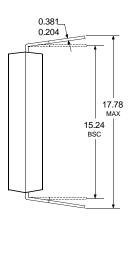
Dimensions in Inches (controlling dimensions)





# Dimensions in Millimeters (for reference only)



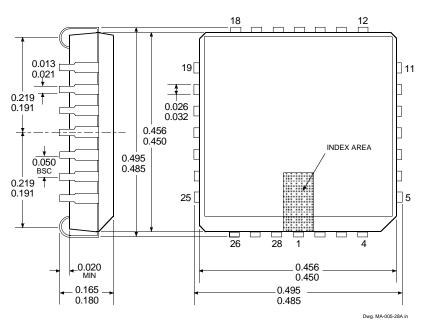


Dwn MA-003-28 in

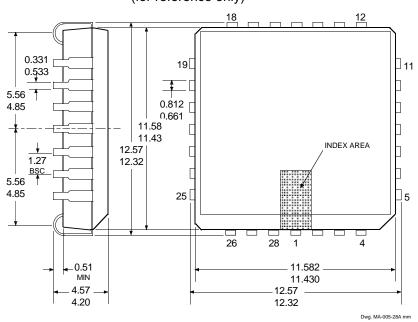
- NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.
  - 2. Lead spacing tolerance is non-cumulative.
  - 3. Lead thickness is measured at seating plane or below.
  - 4. Supplied in standard sticks/tubes of 12 devices.

#### UCN5812EPF

Dimensions in Inches (controlling dimensions)



# Dimensions in Millimeters (for reference only)



NOTES: 1. Exact body and lead configuration at vendor's option within limits shown.

- 2. Lead spacing tolerance is non-cumulative.
- 3. Supplied in standard sticks/tubes of 38 devices or add "TR" to part number for tape and reel.



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# POWER INTERFACE DRIVERS

Function	Output l	Part Number <sup>†</sup>							
SERIAL-INPUT LATCHED DRIVERS									
8-Bit (saturated drivers)	-120 mA	50 V‡	5895						
8-Bit	350 mA	50 V	5821						
8-Bit	350 mA	80 V	5822						
8-Bit	350 mA	50 V‡	5841						
8-Bit	350 mA	80 V‡	5842						
8-Bit (constant-current LED driver)	75 mA	17 V	6275						
8-Bit (constant-current LED driver)	120 mA	24 V	6277						
8-Bit (DMOS drivers)	250 mA	50 V	6595						
8-Bit (DMOS drivers)	350 mA	50 V‡	6A595						
8-Bit (DMOS drivers)	100 mA	50 V	6B595						
10-Bit (active pull-downs)	-25 mA	60 V	5810-F and 6810						
12-Bit (active pull-downs)	-25 mA	60 V	5811						
16-Bit (constant-current LED driver)	75 mA	17 V	6276						
20-Bit (active pull-downs)	-25 mA	60 V	5812-F and 6812						
32-Bit (active pull-downs)	-25 mA	60 V	5818-F and 6818						
32-Bit	100 mA	30 V	5833						
32-Bit (saturated drivers)	100 mA	40 V	5832						
PARALLEI	-INPUT LATCHED	DRIVERS							
4-Bit	350 mA	50 V‡	5800						
8-Bit	-25 mA	60 V	5815						
8-Bit	350 mA	50 V‡	5801						
8-Bit (DMOS drivers)	100 mA	50 V	6B273						
8-Bit (DMOS drivers)	250 mA	50 V	6273						
SPECI	AL-PURPOSE DEV	ICES							
Unipolar Stepper Motor Translator/Driver	1.25 A	50 V‡	5804						
Addressable 8-Bit Decoder/DMOS Driver	250 mA	50 V	6259						
Addressable 8-Bit Decoder/DMOS Driver	350 mA	50 V‡	6A259						
Addressable 8-Bit Decoder/DMOS Driver	100 mA	50 V	6B259						
Addressable 28-Line Decoder/Driver	450 mA	30 V	6817						

<sup>\*</sup> Current is maximum specified test condition, voltage is maximum rating. See specification for sustaining voltage limits. Negative current is defined as coming out of (sourcing) the output.

<sup>‡</sup> Internal transient-suppression diodes included for inductive-load protection.



<sup>†</sup> Complete part number includes additional characters to indicate operating temperature range and package style.